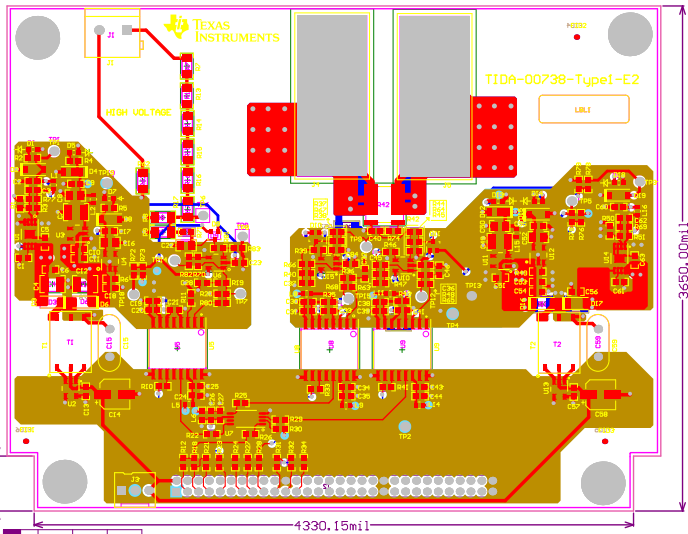


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



Layer Name	Order Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4 High Tg
GD	(.GD)	1.4mil	FR-4 High Tg
PdI	(.GDI)	1.4mil	FR-4 High Tg
Bottom Layer	(.GBL)	1.4mil	FR-4 High Tg
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
4724.41MIL X 3650MIL

Number of Layers : 4
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 7 MIL
 MIN. VIA PAD SIZE: 19.685MIL

MINIMUM ANNULAR RING 0.11mm (4.35MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- .5 MIL, HOLES +/- .3 MIL

MATERIAL:

FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:

REFERENCE: AS SHOWN NO_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:

SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG) ENEPIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCB'S TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES NO
 MICROSECTION: YES IMPEDANCE CONTROL: YES NO
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK



PROJECT TITLE:
ICUM Using AMC1304 and SITARA Controller

DESIGNED FOR:
Public Release

FILE NAME:
TIDA-00738-Type1_E2.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD # : TIDA-00738-Type1	REV : E2	SUN, REV: Not In Use since Control
LAYER NAME : Top, Bottom	DATE : 12/9/2016	TIME : 1:02:38 PM	FILE : TIDA-00738-Type1_E2.PcbDoc
PLOT NAME : Final Layer Composite Printout	GENERATED BY : Sunil Duivedi	DATE : 12/9/2016	TIME : 1:02:38 PM

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ENGINEER: Sunil Duivedi	LAYOUT BY: Avinash
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.14.34663

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